DECLARATION OF COMPLIANCE
- RoHS Declaration -

NXP Semiconductors Netherlands B.V. declares that its certified RoHS compliant semiconductor products (including homogeneous sub-components –pins, casing, and internal parts) are designed to be:

- RoHS compliant meeting the requirements defined under Directive 2011/65/EU of the European Parliament and of the Council of June 8, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (EEE) – recast and its amendments[1]:

RoHS Restricted Substance	Allowable Limit
Cadmium and its compounds	100 ppm (0.01 weight %)
Mercury and its compounds	1000 ppm (0.1 weight %)
Hexavalent chromium and its compounds	1000 ppm (0.1 weight %)
Lead and its compounds	1000 ppm (0.1 weight %)
Polybrominated biphenyls (PBB)	1000 ppm (0.1 weight %)
Polybrominated diphenyl ethers (PBDE)*	1000 ppm (0.1 weight %)
Bis(2-ethylhexyl) phthalate (DEHP)**	1000 ppm (0.1 weight %)
Butyl benzyl phthalate (BBP)**	1000 ppm (0.1 weight %)
Dibutyl phthalate (DBP)**	1000 ppm (0.1 weight %)
Diisobutyl phthalate (DIBP)**	1000 ppm (0.1 weight %)

* This includes also DecaBromoDiphenylEther (Deca-BDE).

** In accordance with amendment under Commission Delegated Directive (EU) 2015/863 of 31 March 2015.

NXP RoHS compliant semiconductor devices contain no more than 0.1% lead (Pb) by weight per homogeneous material, unless used in an application exempted by RoHS. NXP may declare the use of the following RoHS exemptions for RoHS compliant semiconductor devices:

RoHS Exemption	RoHS Exemption Description***
6(c)	Copper alloy containing up to 4 % lead by weight
7(a)	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)
7(c)-I	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
15	Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages
15(a)	Lead in solders to complete a viable electrical connection between the semiconductor die and carrier within integrated circuit flip chip packages where at least one of the following criteria applies: — a semiconductor technology node of 90 nm or larger; — a single die of 300 mm2 or larger in any semiconductor technology node; — stacked die packages with die of 300 mm2 or larger, or silicon interposers of 300 mm2 or larger.

*** Applicable within the scope of categories and expiry dates as given in Annex III of Directive 2011/65/EU

Any semiconductor device that NXP has certified as RoHS compliant declaring Exemption 15 or 15(a) will contain lead (Pb) in solders. These products are RoHS compliant when used in OEM applications covered by these RoHS exemptions permitting lead in solders for applicable categories; expiration dates as listed in Annex III of Directive 2011/65/EU. Applicability of Exemption 15 or 15(a) is dependent on OEM application and final use.

[1] Including amendment under Commission Delegated Directive (EU) 2019/172 of 16 November 2018, regarding exemption 15 for lead in solders.

To facilitate customer requirements and to verify NXP semiconductor product compliance, NXP material content information is available here or by contacting the NXP ECO-Products team at eco-products@nxp.com.

Certification of RoHS compliance of NXP products is reliant upon NXP supplier material content data certifications of each supplied homogenous material in a product(s). The signature below verifies that statements above, including but not limited to material composition data are valid and accurate to the best of our knowledge for NXP products in original sale condition.

28-February-2022

Edwin Bertotti
Director, ECO-Products
NXP Semiconductors